

# Tianyu Yang

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/8190825/publications.pdf>

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10  
papers

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citations

1163117

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docs citations

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times ranked

250  
citing authors

#	ARTICLE	IF	CITATIONS
1	Air Jet Impingement Cooling of Electronic Devices Using Additively Manufactured Nozzles. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 220-229.	2.5	52
2	Phase change material-based thermal energy storage. Cell Reports Physical Science, 2021, 2, 100540.	5.6	51
3	Millimeter-scale liquid metal droplet thermal switch. Applied Physics Letters, 2018, 112, .	3.3	44
4	A composite phase change material thermal buffer based on porous metal foam and low-melting-temperature metal alloy. Applied Physics Letters, 2020, 116, .	3.3	31
5	Phase Change Material Heat Sink for Transient Cooling of High-Power Devices. International Journal of Heat and Mass Transfer, 2021, 170, 121033.	4.8	30
6	An Integrated Liquid Metal Thermal Switch for Active Thermal Management of Electronics. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2341-2351.	2.5	28
7	Nanostructured jumping-droplet thermal rectifier. Physical Review E, 2021, 103, 023110.	2.1	24
8	Equivalent Thermal Conductivity Prediction of Form-Wound Windings With Litz Wire Including Transposition Effects. IEEE Transactions on Industry Applications, 2021, 57, 1440-1449.	4.9	9
9	Heat Spreader Thermal Switch for Power Converter Isothermalization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 1063-1081.	2.5	2
10	Additively Manufactured Impinging Air Jet Cooler for High-Power Electronic Devices. , 2019, , .		1